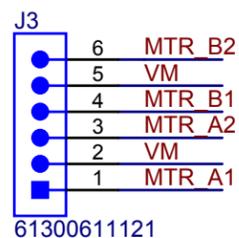
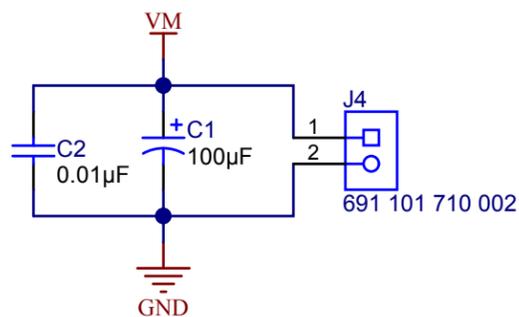
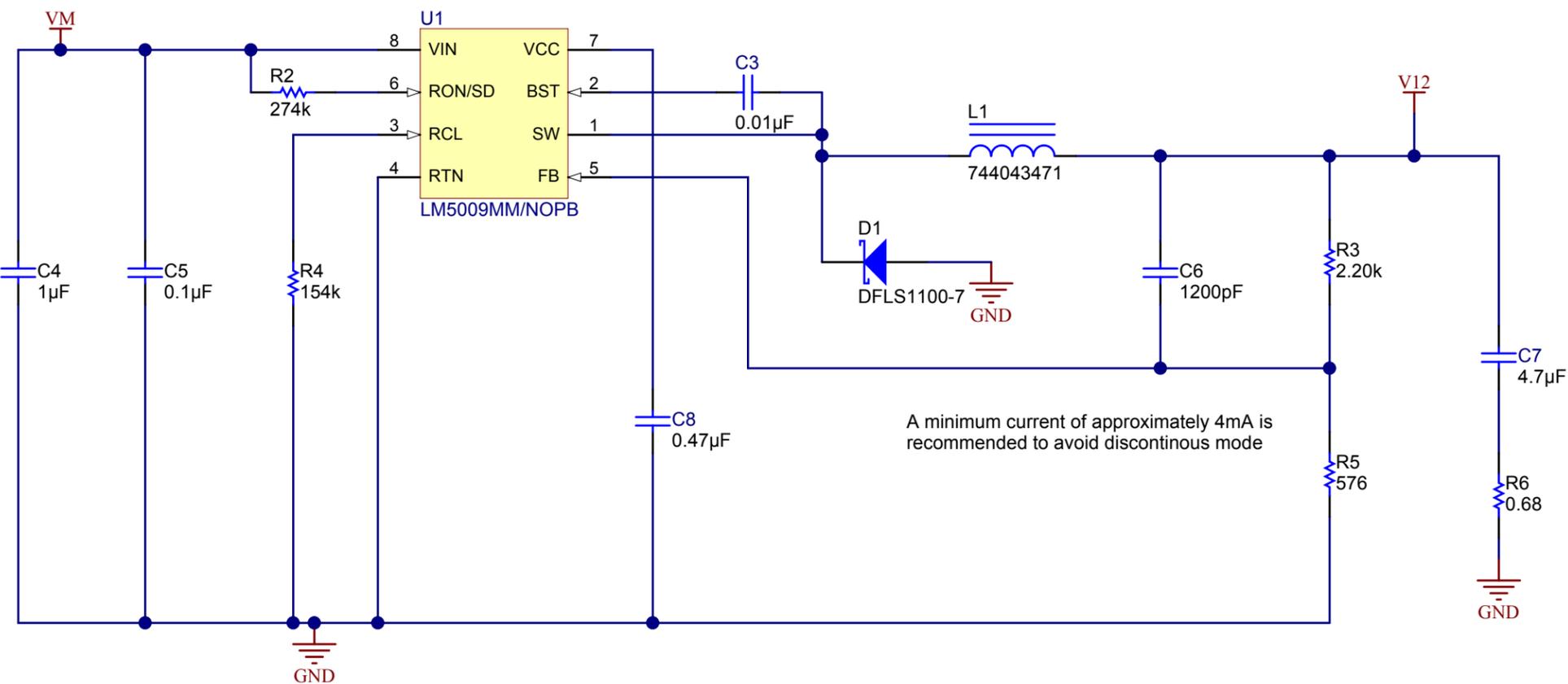
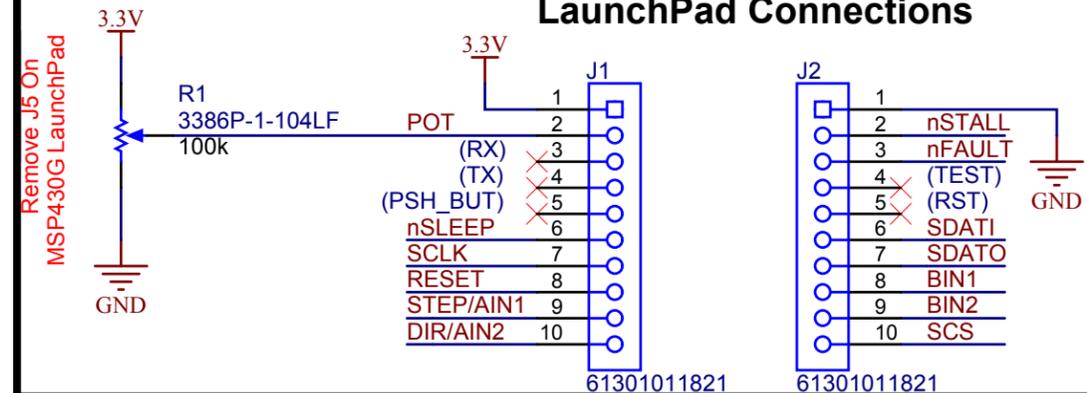


Power/Motor Connections



LaunchPad Connections



PCB LOGO
Pb-Free Symbol

DNP
FID1

PCB LOGO
FCC disclaimer

DNP
FID2

DNP
FID3

PCB LOGO
Texas Instruments

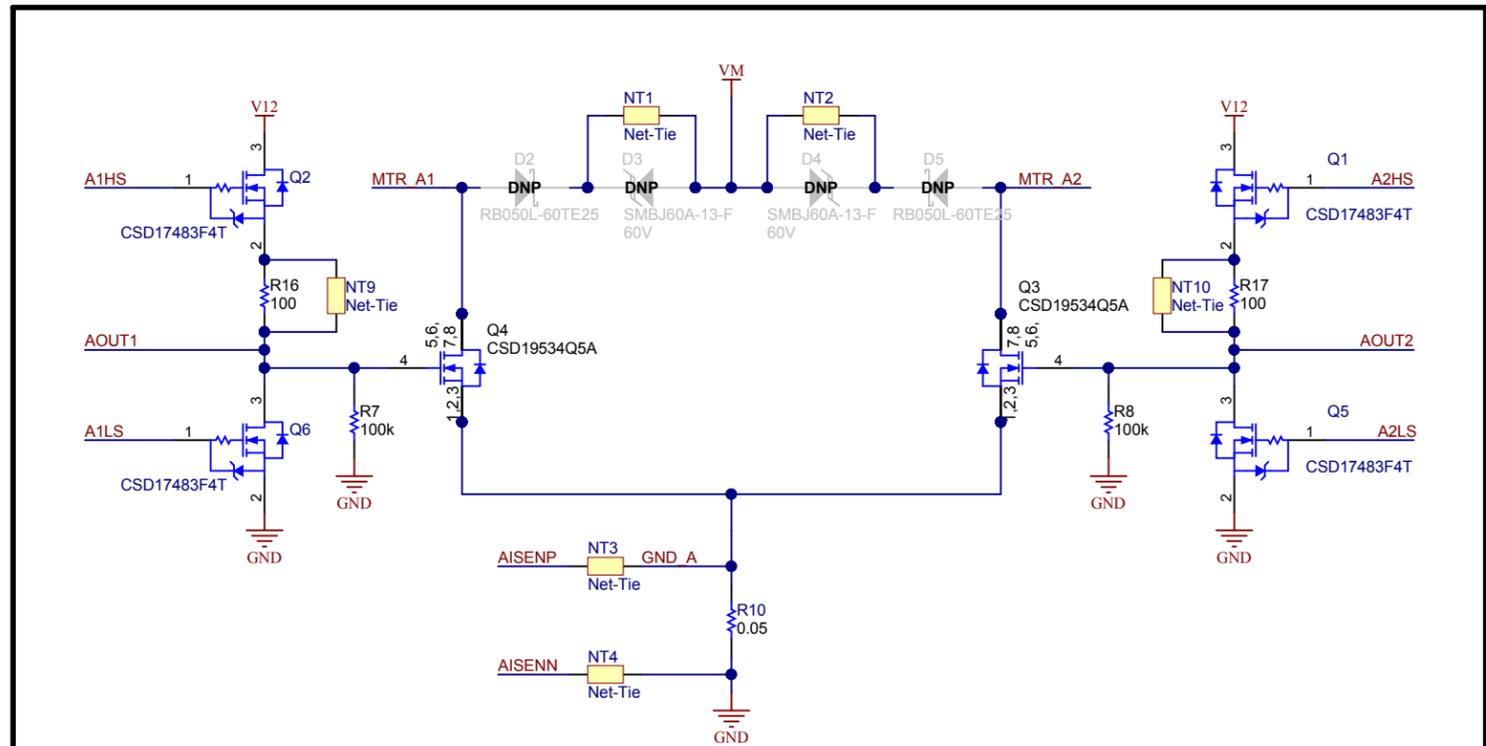
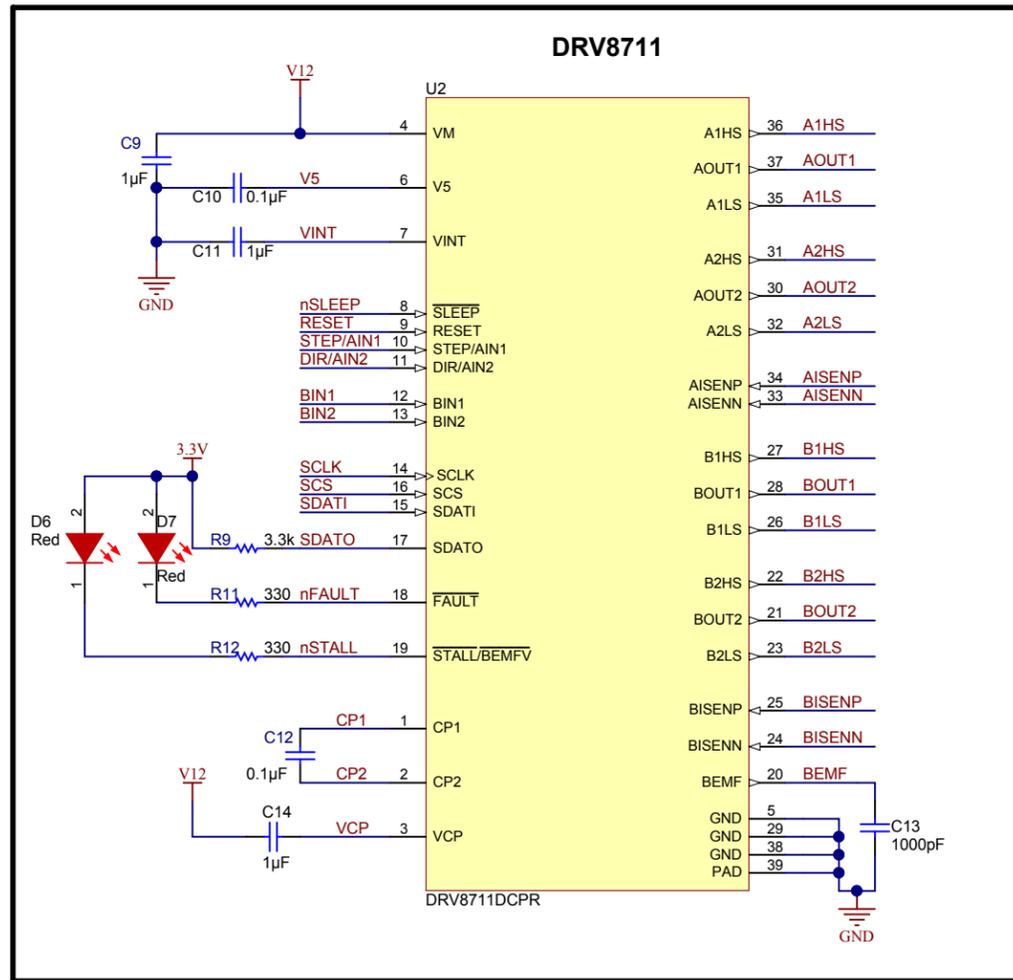
PCB Number: TIDA-00872
PCB Rev: E1

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Number: [TIDA-00872](#) Rev: [E1](#)
 SVN Rev: Version control disabled
 Drawn By:
 Engineer: [Rick Duncan](#)

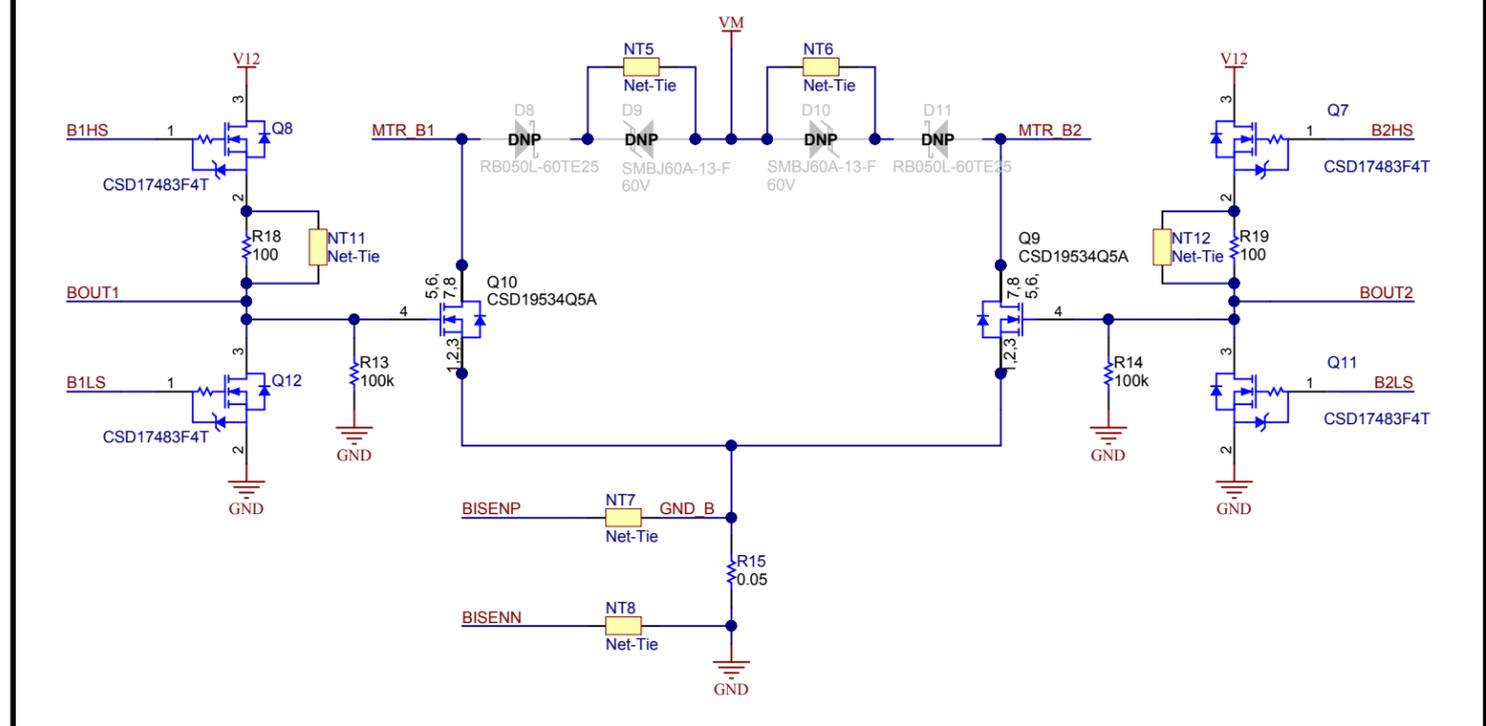
Designed for: [Public Release](#) Mod. Date: 11/16/2015
 Project Title: [Unipolar Stepper Controller](#)
 Sheet Title:
 Assembly Variant: 001 Sheet: 1 of 2
 File: [TIDA-00872_Unipolar.SchDoc](#) Size: A4
 Contact: <http://www.ti.com/support>





Motor MOSFETS plus FETs to limit VGS

To use Avalanche of CSD19534Q5A, leave diodes D2, D5, D8, D11, D3, D4, D9, D10 unpopulated
 To use slow decay, populate diodes D2, D5, D8, and D11
 To use fast decay, populate diodes D2, D5, D8, D11, D3, D4, D9, and D10. Cut Net-Ties NT1, NT2, NT5, and NT6 on bottom of PCB



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